# **Micro-Electrode-Cavity-Array (MECA)** Hahn on a CMOS Chip Mohammad Amayreh<sup>1</sup>, Samar Elsaegh<sup>1</sup>, Markus Kuderer<sup>1</sup>, Schickard Christoph Blattert<sup>1</sup>, Hansjörg Rietsche<sup>1</sup>, Oliver Amft<sup>1,2</sup>

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#### Abstract

This work represents a CMOS-Based nanopore sensing platform for high resolution readout of nanopore events.

### **Measured ASIC Performance**





- CMOS integration reduces the overall capacitance of the readout which reduces the overall noise and thus allows detecting of fast and/or small nanopore events.
- The current readout circuit is configurable for different current ranges and bandwidths and optimized for noise suppression. The circuit is divided into four amplifier stages.
- Noise reduction techniques achieve a total integrated noise of only 18 pA<sub>RMS</sub> in a bandwidth of 1 MHz.
- The ASIC was implemented in a 350 nm standard CMOS technology.
- The ASIC consists of five channels. Four of them are used as a MECA.

# Integration of nanopore biosensor and ASIC



Figure 4: Measured ASIC Performance. (a) ASIC micrograph. (b) Input referred noise power spectrum density PSD of readout circuit.

## **CMOS Post Process**



Figure 1: Schematic diagram of the structure of a nanopore sensor on the CMOS integrated readout circuit (ASIC) and external system components.



Figure 5: CMOS Post process that includes (a) Gold electrode (b) SU8 cavity (by lonera Technologies).

### Circuit diagram, components and specifications of the readout circuit

- The current amplifier (yellow) amplifies the current 100 times.
- The amplified current is converted into a voltage by an integrated transimpedance amplifier (red).
- The output of the TIA is further amplified by the inverting amplifier (green). A fully differential output voltage (blue) is generated to reduce the influence of external sources of interference.

Parameter	OP <sub>1,2</sub>	OP <sub>3</sub>	OP <sub>4</sub>
Input referred voltage noise @1MHZ (nV/√Hz)	2.4	2.84	32
Supply Voltage (V)	±1.65	±1.65	±1.65
Input capacitance amplifier(fF)	750	1600	1440
Input offset Max (mV)	2.2	1.1	14
Gain BW (MHz)	7.3*	12.7**	12**
Phase Margin (deg)	76*	78**	90**
DC gain (dB)	110	117	82

# **Assembly and Packaging**





Maximum input CM (mV) 450 700 160 -1650 Minimum input CM (mV) Supply current (mA) 0.44 \*: at load capacitance of 50pF and feedback factor of 1/7.4 \*: at load capacitane of 10pF and feedback factor of 1 
 Table 1.Summary of OP-Amps
specifications.

Figure 6: Assembly and Packaging: (a) ASIC is bonded on ASIC-PCB (b) Bond wires covered with Epoxy and a seal rubber ring is added (c) Bath electrode is attached (d) ASIC PCB is then inserted into an **Evaluation PCB.** 



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